

## AMENDMENTS TO THE SPECIFICATION

*Please replace the paragraph beginning at page 2, line 32 with the following paragraph:*

Fig. 8 shows a partial sectional view of a semiconductor wafer in a condition wherein a film is formed ideally. In the condition shown in Fig. 8, a metallic film 16 such as a tungsten film is deposited only on a surface (an upper surface in the drawing) of the wafer W, not on a lateral or reverse surface thereof.